

Case 10662302

S13557 U USPT,USOC,EPAB 257/E21.582 and semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2) and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv or (stress near induc\$3 near void\$2))

S13556 U USPT,USOC,EPAB 257/E23.145 and semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2) and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv or (stress near induc\$3 near void\$2))

S13555 U USPT,USOC,EPAB 257/E23.161 and semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2) and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv or (stress near induc\$3 near void\$2))

S13554 U USPT,USOC,EPAB 257/E21.582

S13553 U USPT,USOC,EPAB 257/E23.582

S13552 U USPT,USOC,EPAB 257/E23.145

S13551 U USPT 257/E23.161

S13550 U USPT E23.161.CCLS.

S13549 U USPT 257/E23.161.CCLS.

S13548 U USPT 427/96,337,344,378,380,397.7,384,343.CCLS. and semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2) and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv or (stress near induc\$3 near void\$2))

S13547 U USPT 427/96,337,344,378,380,397.7,384,343.CCLS.

S13546 U USPT 257/758,757,767,774,773,775,781,632642,637,537,759.CCLS. and semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2) and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv or (stress near induc\$3 near void\$2))

<u>S13545</u> U USPT	257/758,757,767,774,773,775,781,632,642,637,537,759.CCLS.
<u>S13544</u> U USPT	257/758,757,767,774,E23.161,E23.145,E21.582,773,775,781,632.CCLS.
<u>S13543</u> U USPT	438/734,618,622,687,637,672,926,781,763,778,622,758.ccls. and semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2) and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv or (stress near induc\$3 near void\$2))
<u>S13542</u> U USPT	438/734,618,622,687,637,672,926,781,763,778,622,758.ccls.
<u>S13541</u> U USPT	(semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv or (stress near induc\$3 near void\$2))) and siv
<u>S13540</u> U USPT	(semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv or (stress near induc\$3 near void\$2))) and void\$3
<u>S13265</u> U USPT (siv or (stress near induc\$3 near void\$2)) and metal\$2 and buffer\$3 and interconnect\$3	2005-01-04 00:39:47
<u>S13264</u> U USPT (siv or (stress near induc\$3 near void\$2)) and metal\$2 and buffer\$3	2005-01-04 00:39:13
<u>S13263</u> U USPT (siv or (stress near induc\$3 near void\$2))	2005-01-04 00:38:32
<u>S13262</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv or (stress near induc\$3 near void\$2))	2005-01-04 00:38:13
<u>S13261</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv\$1 or (stress near(induc\$3 or void\$2)))	2005-01-04 00:36:01
<u>S13260</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv\$2 or (stress near(induc\$3 or void\$2))) and metal\$3	2005-01-04 00:21:32

<u>S13259</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer) and (siv\$2 or (stress near(induc\$3 or void\$2)))	2005-01- 04 00:19:52
<u>S13258</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3 and (buffer\$3 or insulat\$3 or seperat\$3) near (interconnect\$3 or metal or layer)	2005-01- 04 00:17:41
<u>S13257</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3 and (buffer\$3 or insulat\$3) near (interconnect\$3 or metal or layer)	2005-01- 04 00:16:38
<u>S13256</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3 and buffer\$3	2005-01- 04 00:15:36
<u>S13255</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2)and siv\$3	2005-01- 04 00:15:09
<u>S13254</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2) and (first or second or two) near interconnect\$3 and siv\$3 and buffer\$3	2005-01- 03 23:58:44
<u>S13253</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2) and (first or second or two) near interconnect\$3 and siv\$3	2005-01- 03 23:52:12
<u>S13252</u> U USPT semiconductor\$2 and interconnect\$3 and (via\$2 or hole\$2) and (first or second or two) near interconnect\$3	2005-01- 03 23:43:17
<u>S13251</u> U USPT semiconductor near process and (thermopile near (sensor\$2 or detector\$2) or infared\$2 near (sensor\$2 or detector\$2))	2005-01- 03 14:29:42
<u>S13250</u> U USPT semiconductor near process	2005-01- 03 14:29:13